

[UNDER BUMP METALLURGY LAYER]

Abstract

The present invention relates to an under bump metallurgy layer, comprising an adhesion layer, a barrier layer and a wetting– barrier layer. The adhesion layer, the barrier layer and the wetting– barrier layer are arranged sequentially on the pad of the chip, and the wetting– barrier layer is disposed between the barrier layer and the bump. The wetting– barrier layer, containing nickel, can improve the bonding ability between the pad and the bump. Also, the invention relates to a flip chip structure including at least a chip, a plurality of bumps and the under bump metallurgy mentioned above.